

	Type	Hits	Search Text	DBs
1	BRS	0	US-U5834339-\$.DID. OR US-U6107123-\$.DID. OR US-U6000924-\$.DID. OR US-U6187613-\$.DID. OR US-U6255142-\$.DID. OR US-U6046076-\$.DID.	USPAT
2	BRS	6	US-5834339-\$.DID. OR US-6107123-\$.DID. OR US-6000924-\$.DID. OR US-6187613-\$.DID. OR US-6255142-\$.DID. OR US-6046076-\$.DID.	USPAT
3	BRS	1184304	mcm or multi adj chip or "multi-chip" or chip or ic or integrated adj circuit or package near2 (semiconductor or silicon)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
4	BRS	1904789	encapsulat\$6 or resin	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
5	BRS	23440	(swip\$6 or wip\$4 or push\$4 or pull\$4 or forc\$4 or thrust\$4 or shov\$4) near4 (encapsulat\$6 or resin)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
6	BRS	1020	((swip\$6 or wip\$4 or push\$4 or pull\$4 or forc\$4 or thrust\$4 or shov\$4) near4 (encapsulat\$6 or resin)) same (mcm or multi adj chip or "multi-chip" or chip or ic or integrated adj circuit or package near2 (semiconductor or silicon))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
7	BRS	4	((swip\$6 or wip\$4 or push\$4 or pull\$4 or forc\$4 or thrust\$4 or shov\$4) near4 (encapsulat\$6 or resin)) same (mcm or multi adj chip or "multi-chip" or chip or ic or integrated adj circuit or package near2 (semiconductor or silicon)) same stencil\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
8	BRS	28	((swip\$6 or wip\$4 or push\$4 or pull\$4 or forc\$4 or thrust\$4 or shov\$4) near4 (encapsulat\$6 or resin)) same (mcm or multi adj chip or "multi-chip" or chip or ic or integrated adj circuit or package near2 (semiconductor or silicon)) and stencil\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB

	Type	Hits	Search Text	DBs
9	BRS	27	(((((swip\$6 or wip\$4 or push\$4 or pull\$4 or forc\$4 or thrust\$4 or shov\$4) near4 (encapsulat\$6 or resin)) same (mcm or multi adj chip or "multi-chip" or chip or ic or integrated adj circuit or package near2 (semiconductor or silicon)) and stencil\$4) and (@ad < "20030312"))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
10	BRS	621778	squeegee or wiper or swiper or blade	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
11	BRS	4278	((squeegee or wiper or swiper or blade) near4 (encapsulat\$6 or resin))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
12	BRS	2	(((((squeegee or wiper or swiper or blade) near4 (encapsulat\$6 or resin)) same (mcm or multi adj chip or "multi-chip" or chip or ic or integrated adj circuit or package near2 (semiconductor or silicon)) and stencil\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
13	BRS	114	(((((squeegee or wiper or swiper or blade) near4 (encapsulat\$6 or resin)) same (mcm or multi adj chip or "multi-chip" or chip or ic or integrated adj circuit or package near2 (semiconductor or silicon))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
14	BRS	633	(((((squeegee or wiper or swiper or blade) same (encapsulat\$6 or resin) same (mcm or multi adj chip or "multi-chip" or chip or ic or integrated adj circuit or package near2 (semiconductor or silicon))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
15	BRS	598	(((((squeegee or wiper or swiper or blade) same (encapsulat\$6 or resin) same (mcm or multi adj chip or "multi-chip" or chip or ic or integrated adj circuit or package near2 (semiconductor or silicon))) and (@ad < "20030312"))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB

	Type	Hits	Search Text	DBs
16	BRS	103	(squeeze or wiper or swiper or blade) near8 (encapsulat\$6 or resin) near8 (mcm or multi adj chip or "multi-chip" or chip or ic or integrated adj circuit or package near2 (semiconductor or silicon))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
17	BRS	96	((squeeze or wiper or swiper or blade) near8 (encapsulat\$6 or resin) near8 (mcm or multi adj chip or "multi-chip" or chip or ic or integrated adj circuit or package near2 (semiconductor or silicon))) and (@ad < "20030312")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
18	BRS	626400	squeeze or wiper or swiper or blade or sweeper	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
19	BRS	103	(squeeze or wiper or swiper or blade or sweeper) near8 (encapsulat\$6 or resin) near8 (mcm or multi adj chip or "multi-chip" or chip or ic or integrated adj circuit or package near2 (semiconductor or silicon))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
20	IS&R	1499	((438/112) or (438/124) or (438/126)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
21	BRS	1323	((((438/112) or (438/124) or (438/126)).CCLS.) and (@ad < "20030312"))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
22	BRS	105	((((438/112) or (438/124) or (438/126)).CCLS.) and (@ad < "20030312")) and (squeeze or wiper or swiper or blade or sweeper)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB

	Type	Hits	Search Text	DBs
23	BRS	103	((((438/112) or (438/124) or (438/126)).CCLS.) and (@ad < "20030312")) and (squeegee or wiper or swiper or blade or sweeper)) not (((squeegee or wiper or swiper or blade) near8 (encapsulat\$6 or resin) near8 (mcm or multi adj chip or "multi-chip" or chip or ic or integrated adj circuit or package near2 (semiconductor or silicon))) and (@ad < "20030312"))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB